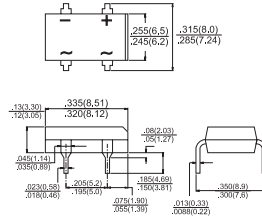


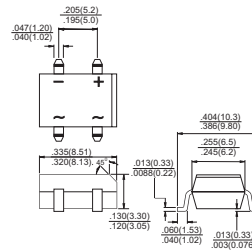
DB



Features

- ✧ UL Recognized File # E-96005
- ✧ Glass passivated junction
- ✧ Ideal for printed circuit board
- ✧ Reliable low cost construction utilizing molded plastic technique
- ✧ High temperature soldering guaranteed:
260 °C / 10 seconds / 0.375" (9.5mm)
lead length at 5 lbs., (2.3 kg) tension
- ✧ Small size, simple installation
Pure tin plated, Lead free. Leads solderable
per MIL-STD-202, Method 208
- ✧ High surge current capability

DBS



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	DB	DB	DB	DB	DB	DB	DB	Units
		101G	102G	103G	104G	105G	106G	107G	
		DBS	DBS	DBS	DBS	DBS	DBS	DBS	
		101G	102G	103G	104G	105G	106G	107G	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @ $T_A = 40^\circ C$	$I_{(AV)}$	1.0							A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	50							A
Maximum Instantaneous Forward Voltage @ 1.0A	V_F	1.1							V
Maximum DC Reverse Current @ $T_A=25^\circ C$ at Rated DC Blocking Voltage @ $T_A=125^\circ C$	I_R	10 500							μA μA
Typical Thermal resistance (Note 1)	$R_{\theta JA}$ $R_{\theta JL}$	40 15							$^\circ C/W$
Operating Temperature Range	T_J	-55 to +150							$^\circ C$
Storage Temperature Range	T_{STG}	-55 to +150							$^\circ C$

- Notes:
1. Thermal Resistance from Junction to Ambient and from Junction to Lead Mounted On P.C.B. with 0.2" x 0.2" (5mm x 5mm) Copper Pads.
 2. DBS for Surface Mount Package.

RATINGS AND CHARACTERISTIC CURVES (DB(S)101G THRU DB(S)107G)

FIG.1- MAXIMUM DERATING CURVE FOR OUTPUT RECTIFIED CURRENT

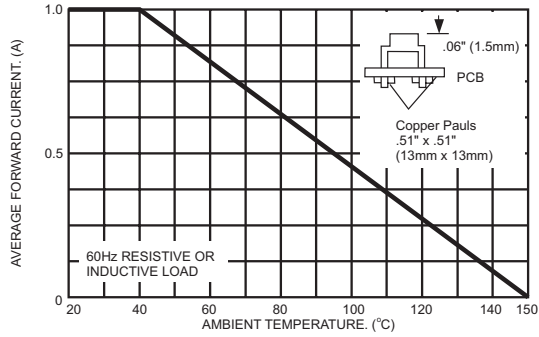


FIG.2- TYPICAL REVERSE CHARACTERISTICS PER BRIDGE ELEMENT

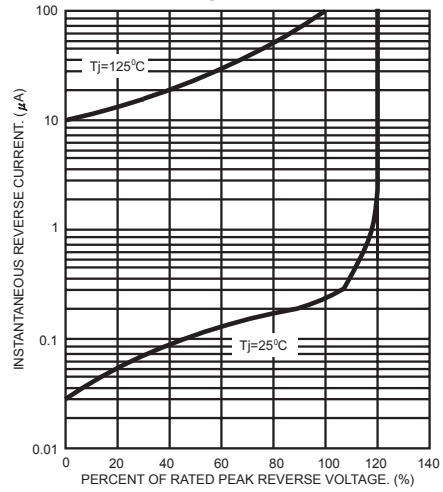


FIG.3- MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

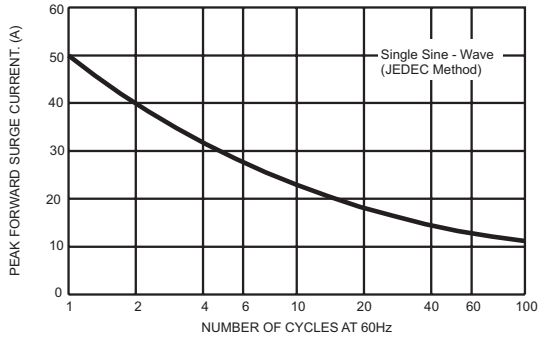


FIG.4- TYPICAL JUNCTION CAPACITANCE PER BRIDGE ELEMENT

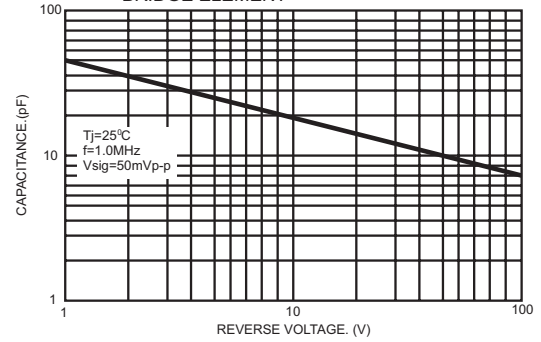
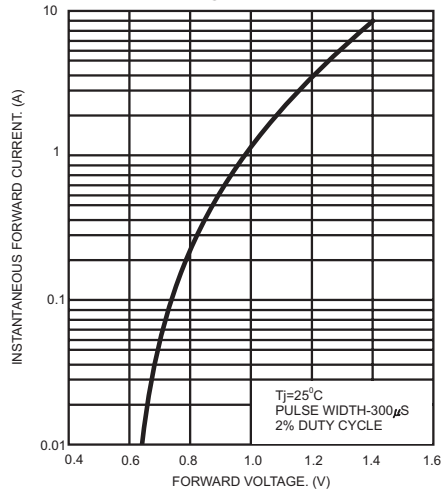


FIG.5- TYPICAL FORWARD CHARACTERISTICS PER BRIDGE ELEMENT



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[DB103G](#) [DBS101G](#)